

## A BREAKTHROUGH MEMS MICROPHONE CONCEPT

Loïc JOET

# A GROWING MARKET, REQUIRING HIGHER PERFORMANCES

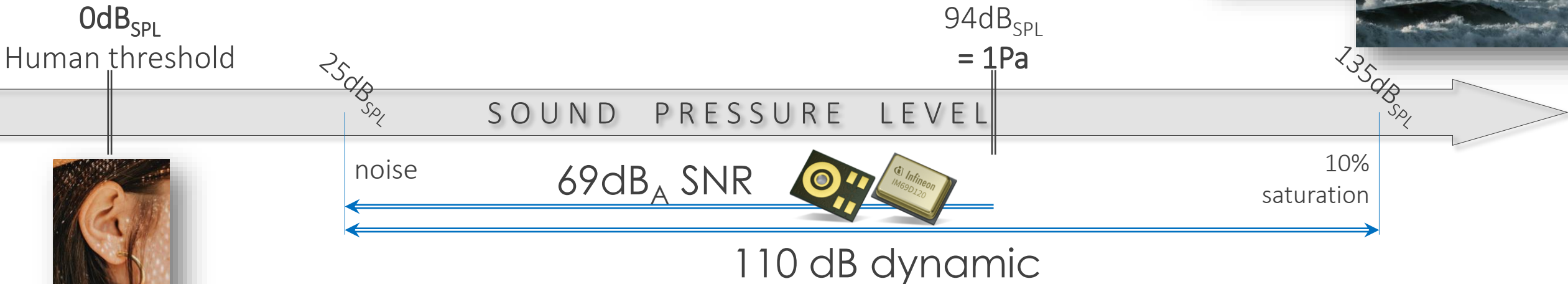
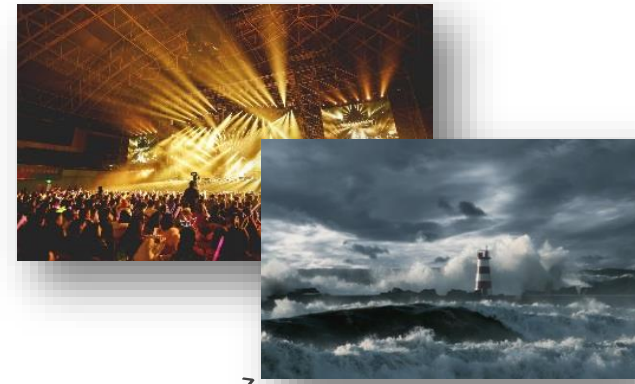
## A better SNR ...

- **High fidelity** conversation/video
- **Noise cancelation** enhancement
- **Range** increase
- **Speech recognition** improve
- **New applications:** surveillance

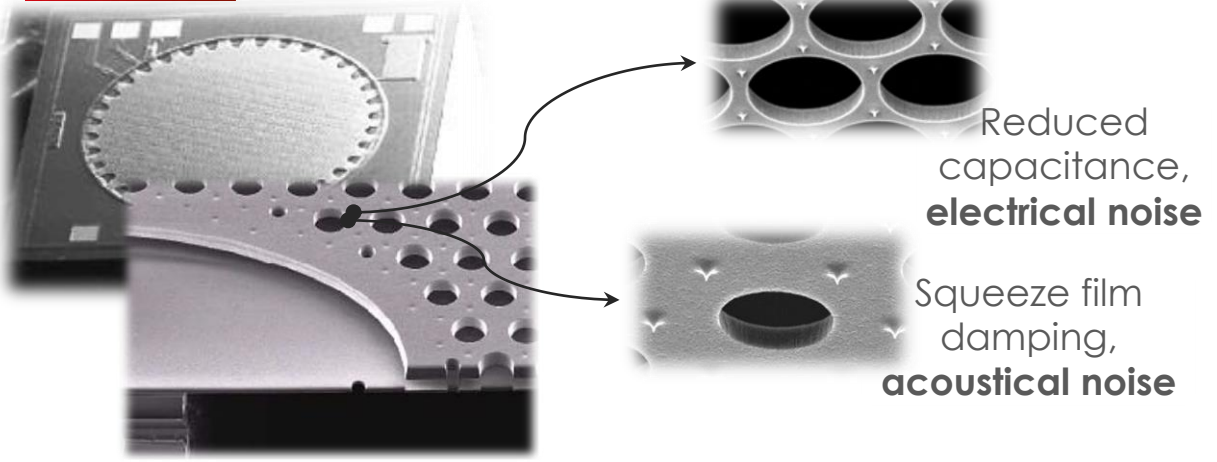
Maintaining the AOP

Extending the bandwidth to 20kHz

Maintaining the size



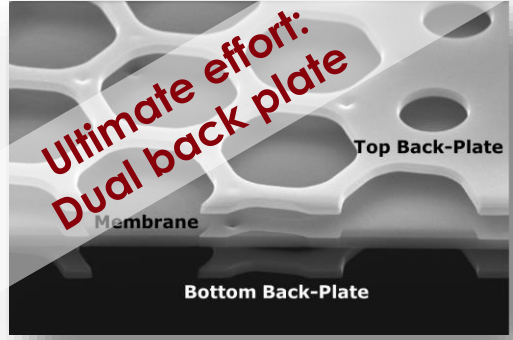
# CURRENT CAPACITIVE MICROPHONES HAVE REACHED THEIR LIMITS



Today highest perf.



- 69dB(A) SNR
- 4 x 3 x 1.2 mm<sup>3</sup>
- ~ 10mm<sup>3</sup> BV



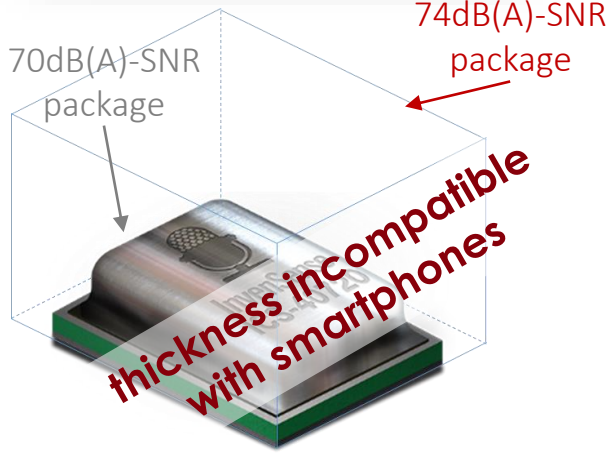
2006



SNR	59dB(A)	60dB(A)	61dB(A)	64dB(A)	66dB(A)
Sample					
Die size	0.64mm <sup>2</sup>	0.81mm <sup>2</sup>	1.0mm <sup>2</sup>	1.44mm <sup>2</sup>	1.96mm <sup>2</sup>
Back volume	1.1mm <sup>3</sup>	1.1mm <sup>3</sup>	1.1mm <sup>3</sup>	3.0mm <sup>3</sup>	3.0mm <sup>3</sup>

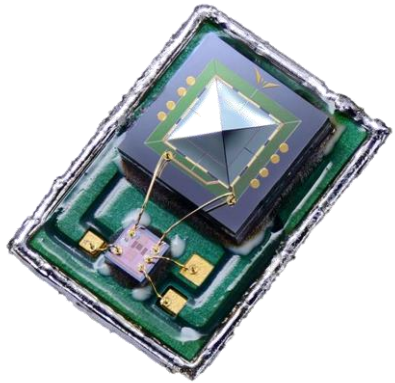


- 74dB(A) SNR
- 4.7 x 3.8 x 3.5 mm<sup>3</sup>
- ~ 45mm<sup>3</sup> BV



A breakthrough is required ...  
Backplate must be removed!

# PIEZOELECTRIC MICROPHONES STRUGGLE TO PROVIDE MORE PERFORMANCES



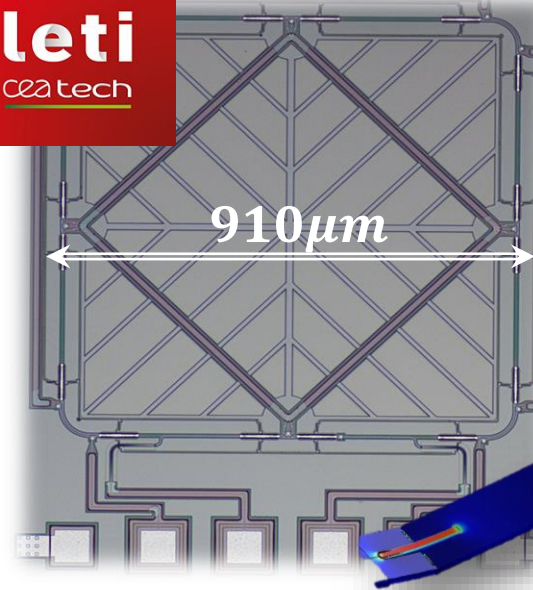
## 63dB(A)-SNR:

6dB lower than Infineon (same package)

- small amount of charges / large capa
- leaks between flaps (roll-off @ 85Hz)
- $\tan(\delta)$  intrinsic noise

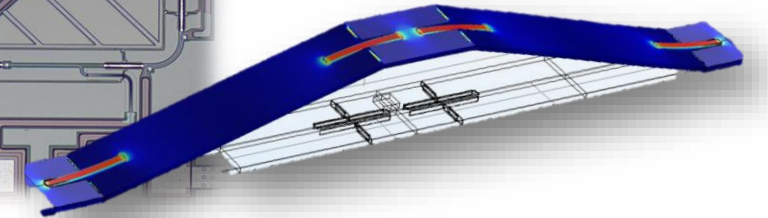
Vesper punch line:

**“very high performances”**  
**“very low power consumption”**



## 70dB(A)-SNR

- Rigid piston
- Lever arm :  
Compliance matching  
Stress concentration in smaller AlN patches



Low cost / good performances...  
Not the breakthrough!

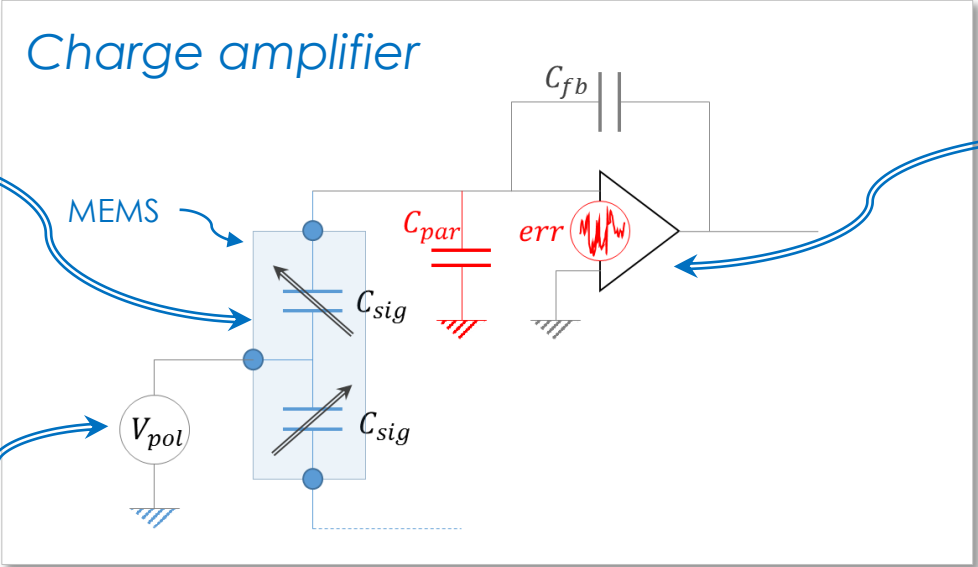
# CAPACITIVE TRANSDUCTION IS REALLY EFFICIENT

$$\left(\frac{\delta C_{sig}}{C_{sig}}\right)_{max} = 10\%$$

non linearity < 5%

15V polarization

Main advantage!



10nV/√Hz input noise amplifier

Conventional ...

120dB dynamic reachable!

$$\Rightarrow \frac{C_{sig}}{C_{par} + C_{fb}} = 1.1$$

Capacitive transduction efficiency without the backplate noise?

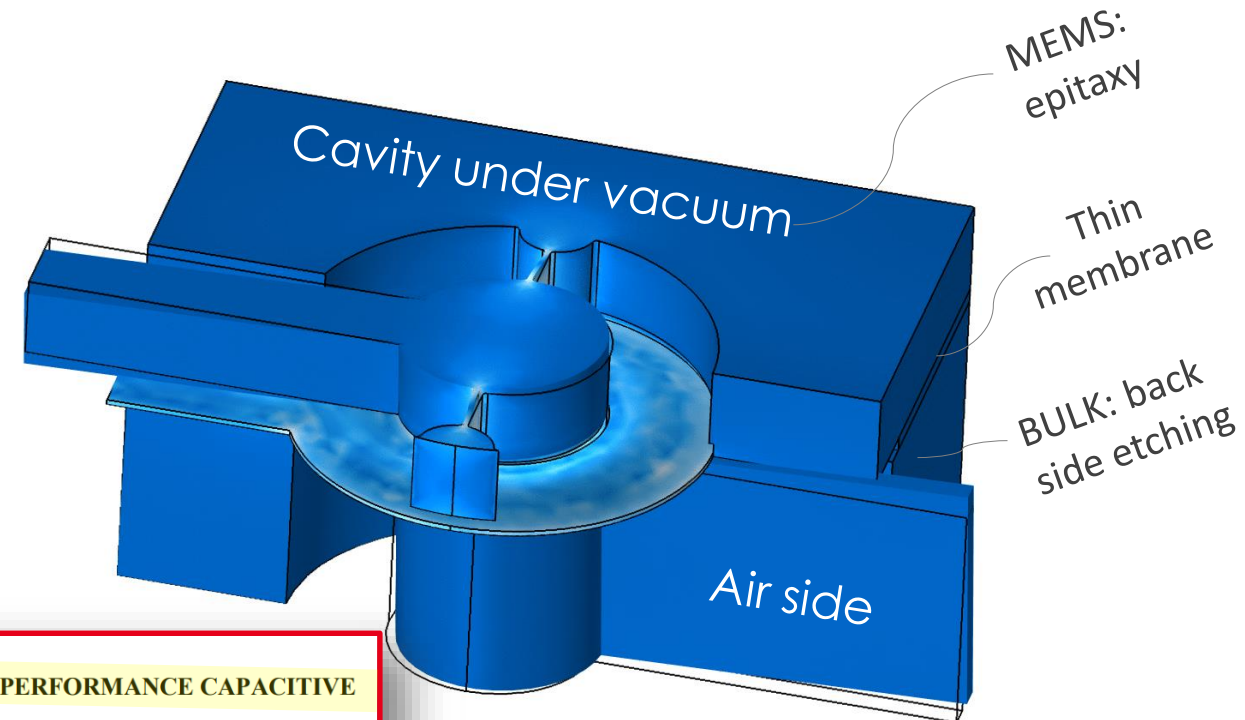
# LET'S PUT THE ELECTRODES INTO VACUUM!

A simple idea ...

... masking a complex implementation!

- Transmit displacement to vacuum,
- Resist to 10bars,
- Stay insensitive to atmospheric pressure variation
- ...

An innovative air-to-vacuum hinge:



17:30 - 17:45

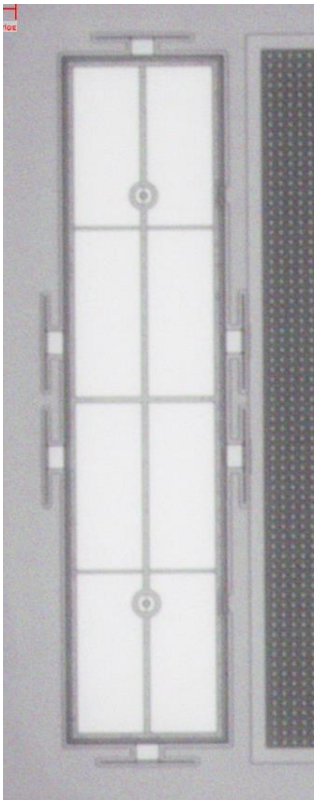
**W4E.005 NOVEL HINGE MECHANISM FOR VACUUM TRANSDUCTION HIGH PERFORMANCE CAPACITIVE MEMS MICROPHONES**

Samer Dagher<sup>1,2</sup>, Carine Ladner<sup>1</sup>, Stéphane Durand<sup>2</sup>, and Loic Joet<sup>1</sup>

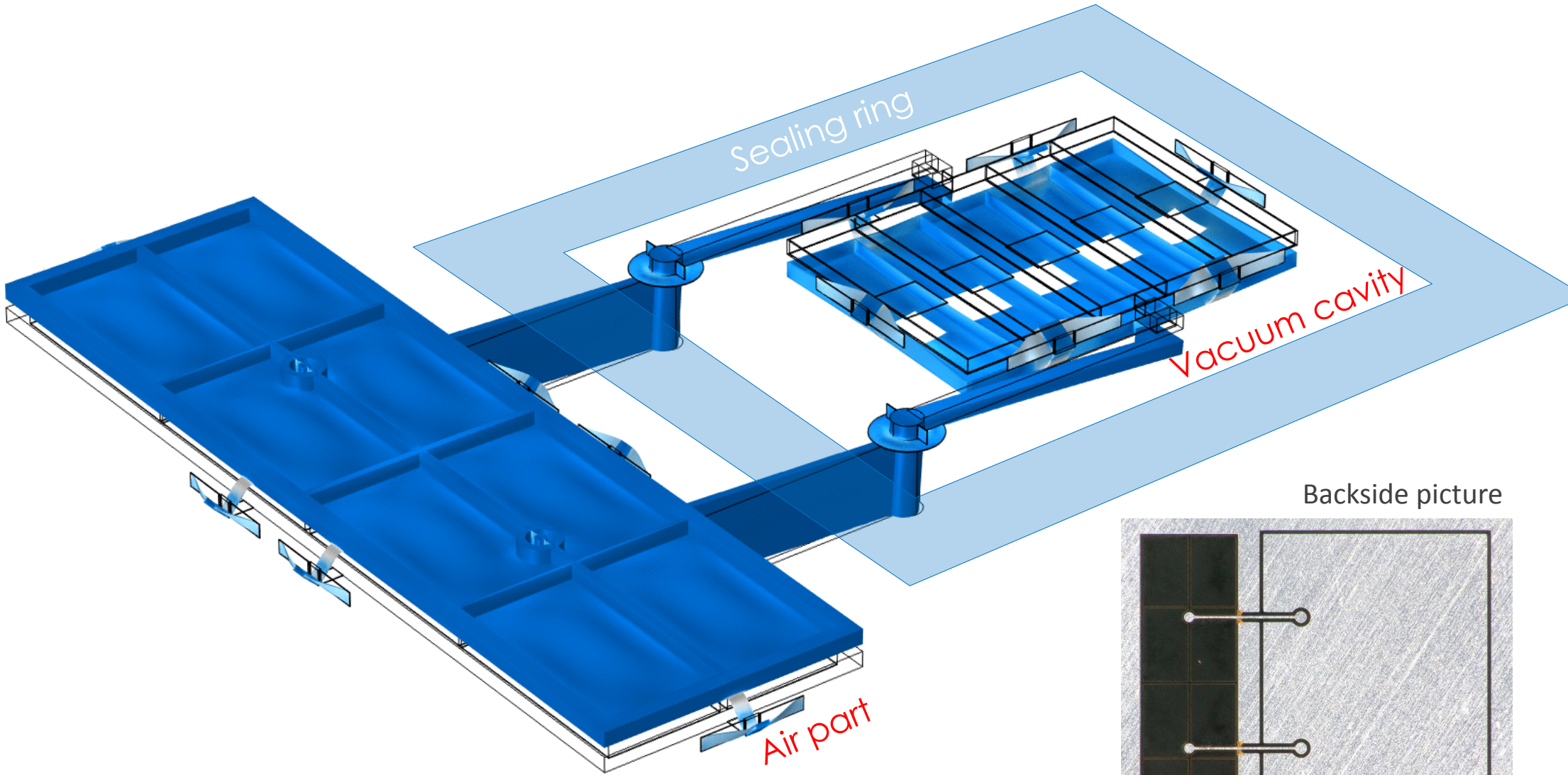
<sup>1</sup>University of Grenoble, Aples CEA-Leti, FRANCE and <sup>2</sup>LAUM UMR-CNRS, FRANCE

Design, fabrication and first experimental results of a microscale hinge mechanism allowing the mechanical transfer of a force between two atmospheres. Applied to the design of a capacitive MEMS microphone, this mechanism divides the device into two separate parts: a pressure harvesting membrane in air, linked to a capacitive transducer sitting in vacuum. Theoretically this separation should increase overall microphone performance (SNR>75dB(A)) while maintaining a small device footprint (<2mm<sup>2</sup>).

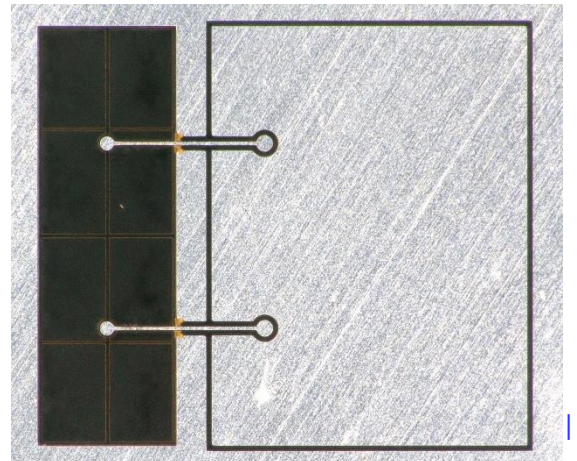
# FROM HINGES TO MICROPHONE



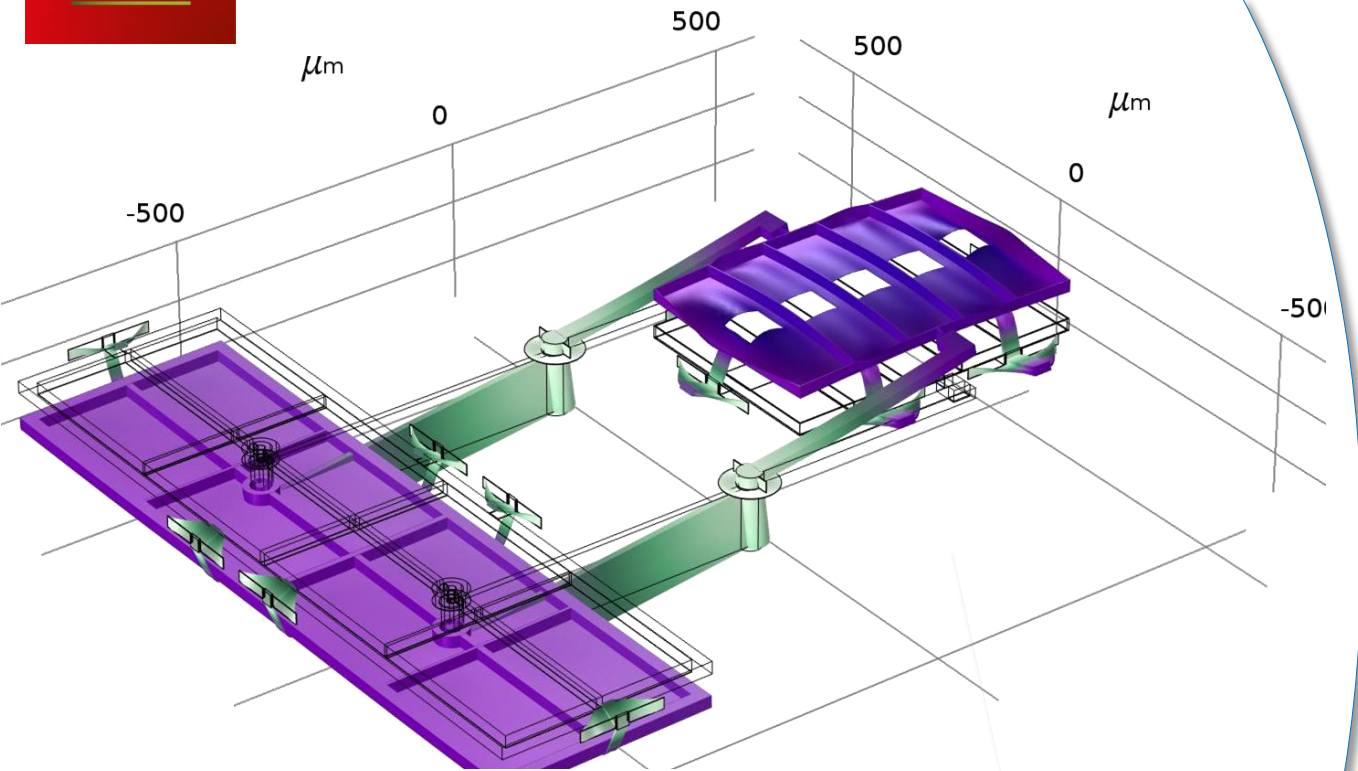
MEMS IR picture before cap sealing



Backside picture



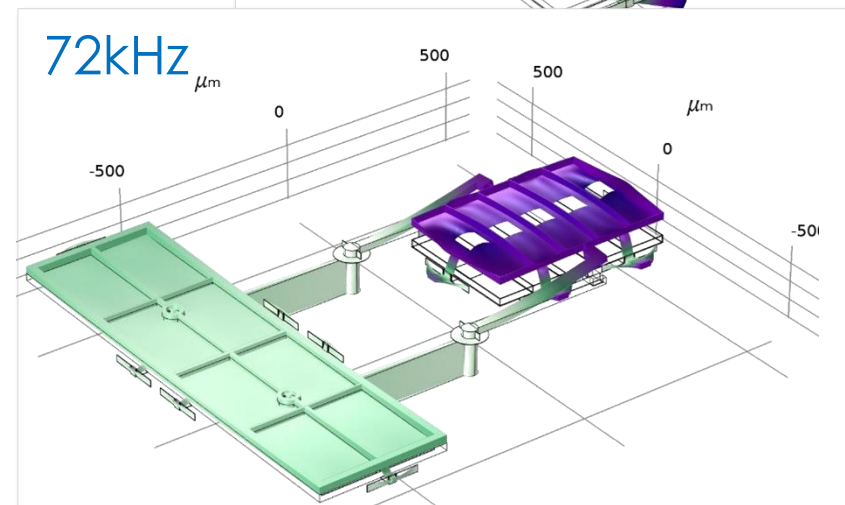
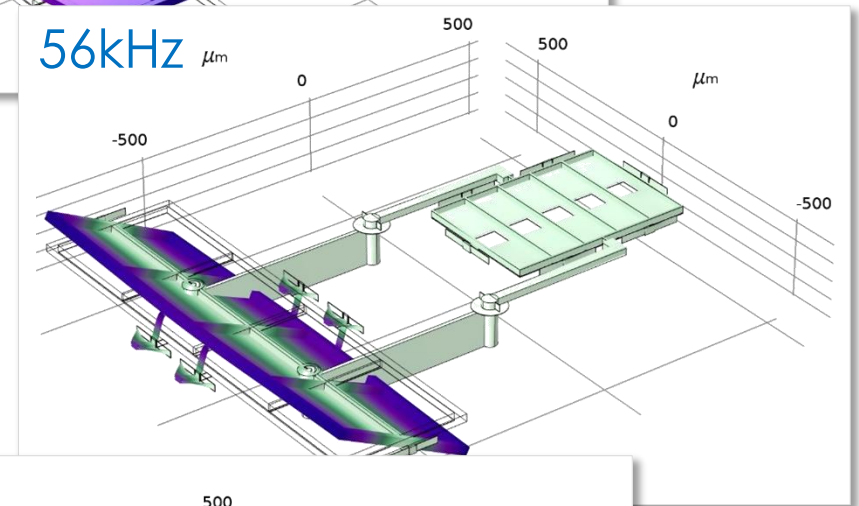
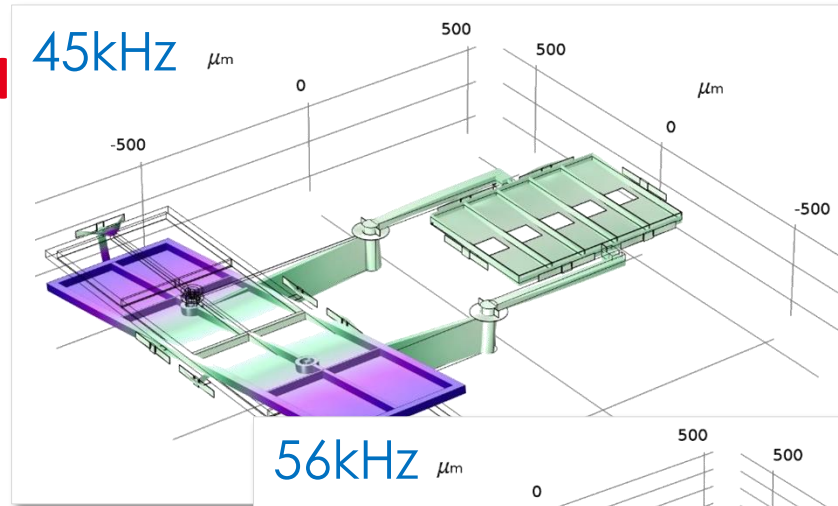
# MECHANICAL PART: COMPATIBLE WITH HI



1st mode at **36kHz** = useful mode

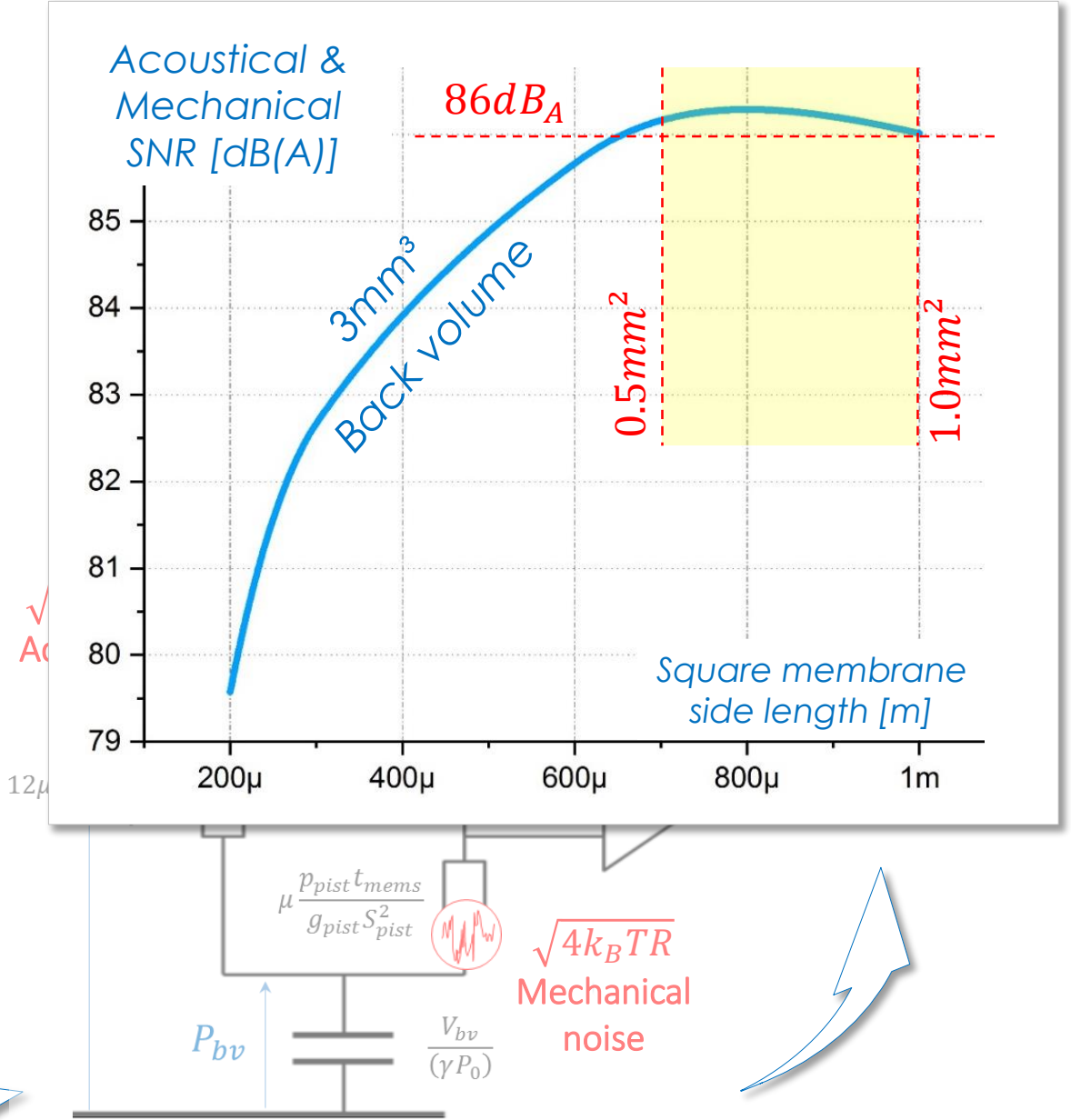
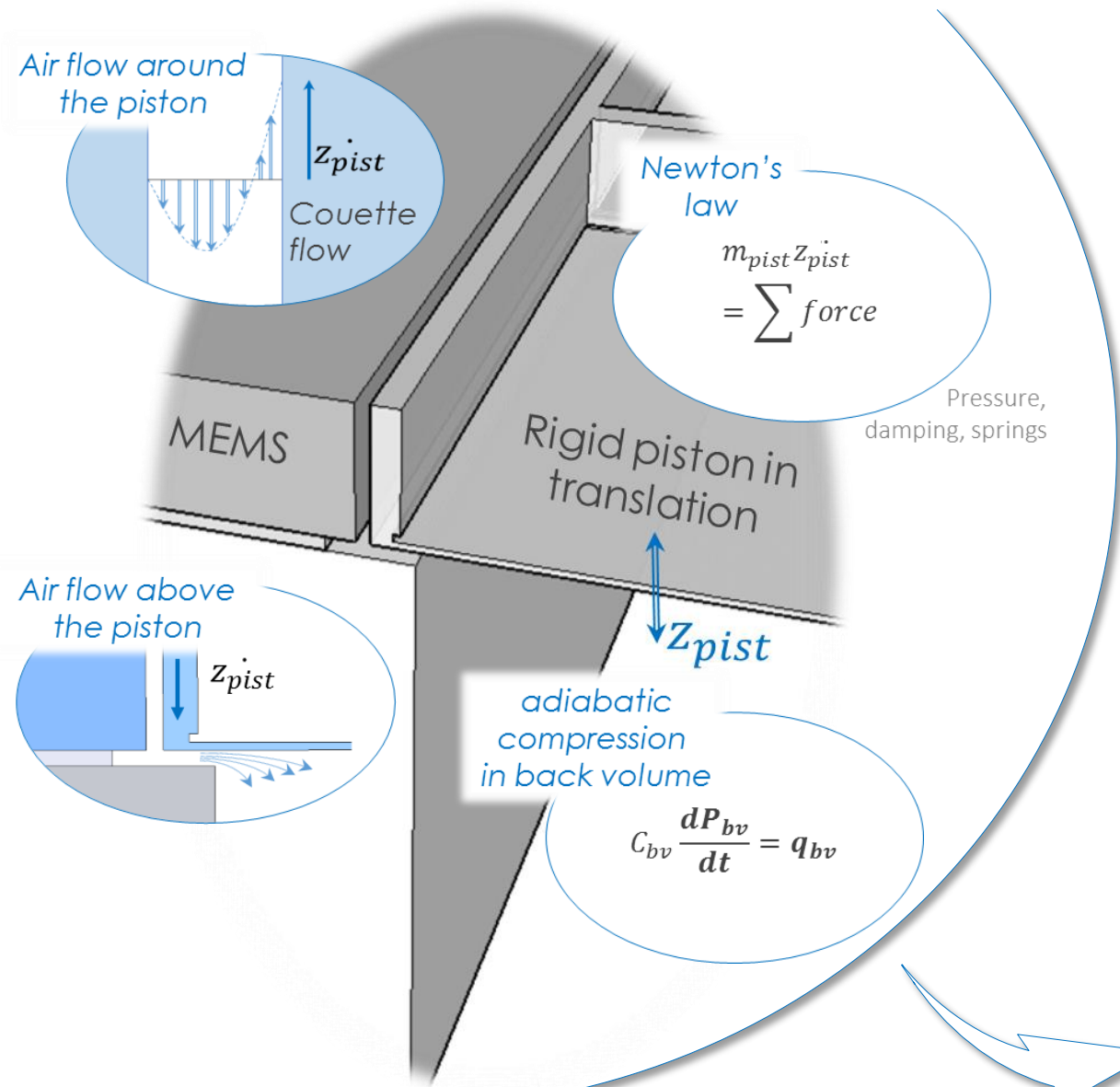
Stiff and light

- 1μm piston / electrode
- 20μm MEMS Skeleton



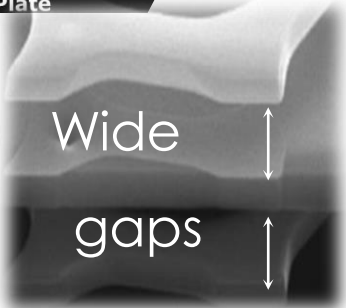
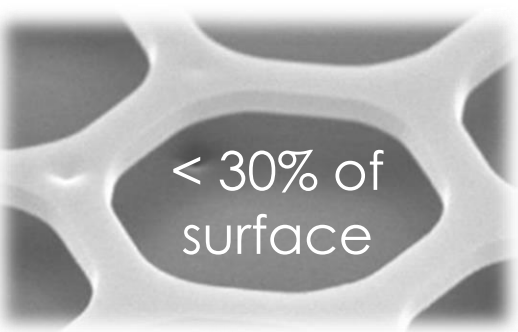
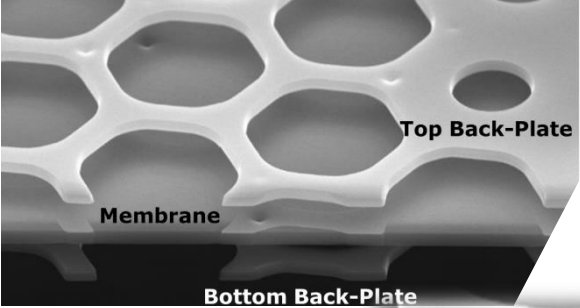


# ACOUSTICAL PART: COMPATIBLE WITH HIGH SNR

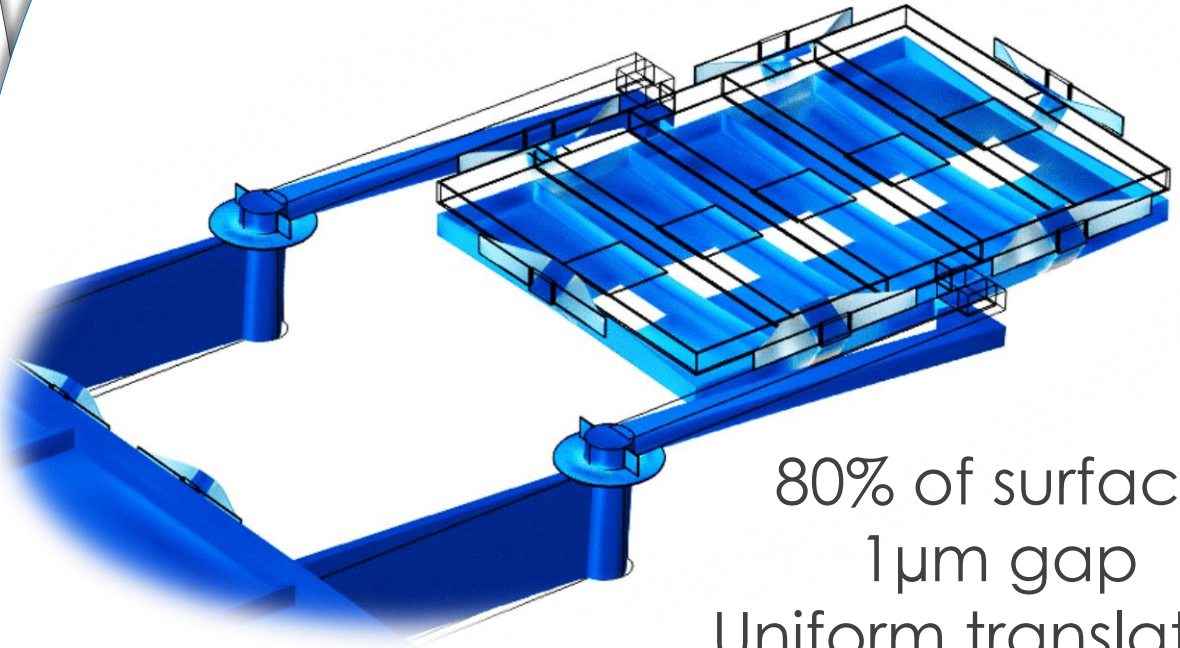


# ELECTRICAL PART: COMPATIBLE WITH HIGH CAPACITANCE DENSITY

Squeeze film damping reduction



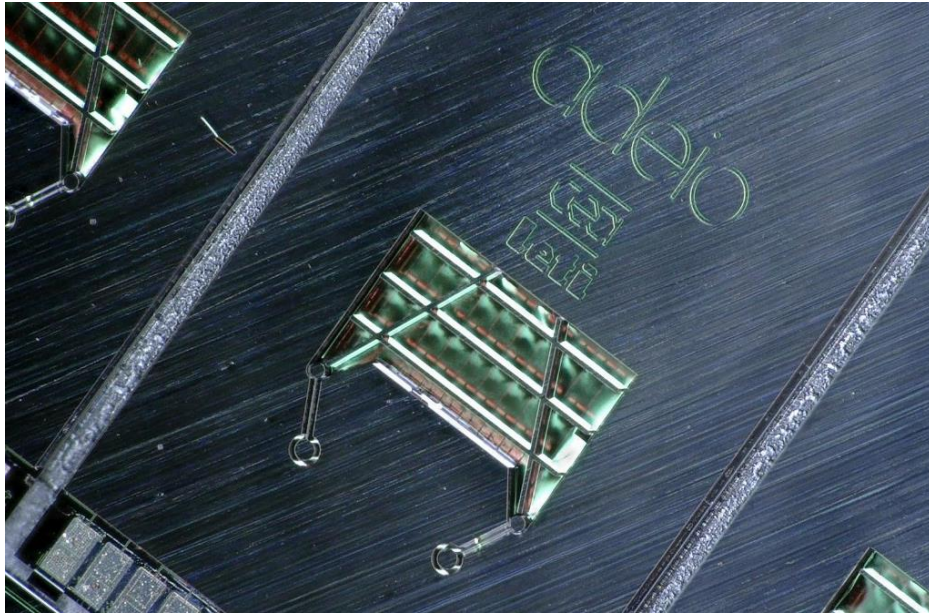
Capacitive transduction optimization



**8x higher** capacitance density  
**Dynamic > 120dB** reachable

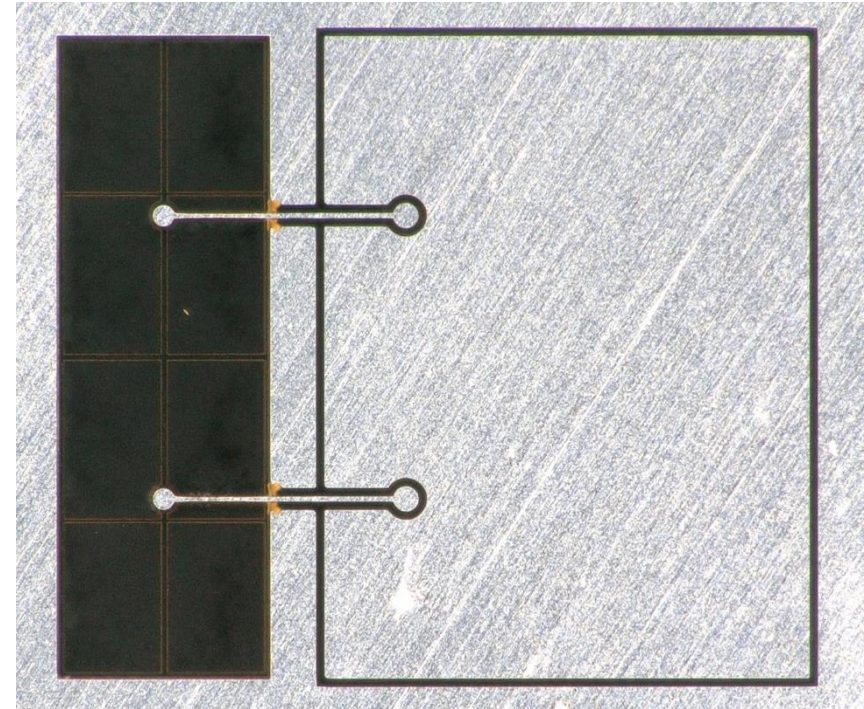
# PROJECT STATUS

2018: first realization



Proof-of-concept of  
air-to-vacuum transmission

Currently in clean room



Expected performances:

- 75dB(A)-SNR
- 3mm<sup>3</sup> backvolume
- 135dB<sub>SPL</sub> AOP (10% saturation)
- 20kHz bandwidth